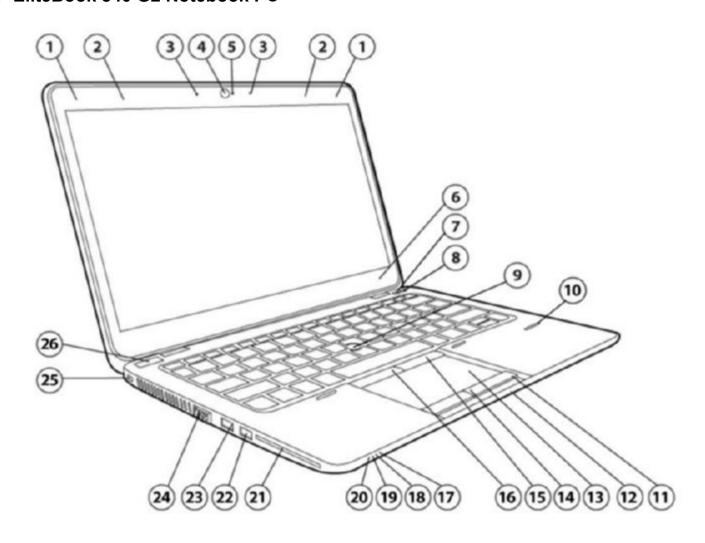
Overview

HP EliteBook 840 G2 Notebook PC



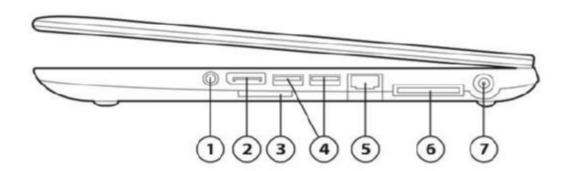
Front/Left

- 1. WLAN antennas (2)
- 2. WWAN antennas (2)
- 3. Internal microphones (2)
- 4. Webcam (select models only)
- 5. Webcam light (select models only)
- 6. Internal display switch
- 7. Wireless button
- 8. Volume mute button
- 9. Pointstick
- 10. Fingerprint reader (optional)
- 11. Right TouchPad button
- 12 NFC sensor (optional)
- 13. TouchPad zone

- 14. Left TouchPad button
- 15. Right pointing stick button
- 16. Left pointing stick button
- 17. Hard drive light
- 18. AC adapter/Battery light
- 19. Power light
- 20. Wireless light
- 21. Smart card reader
- 22. USB 3.0 port
- 23. USB 3.0 charging port
- 24. External VGA monitor port
- 25. Security cable slot
- 26. Power button



Overview



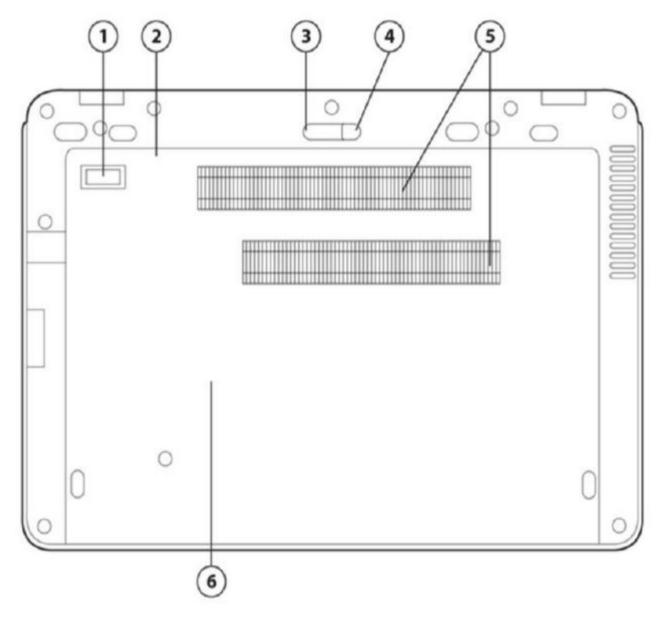
Right

- Audio-out (headphone) jack/Audio-in(microphone) jack
- 2. DisplayPort
- 3. Memory card reader
- 4. USB 3.0 ports (2)

- 5. Drop-jaw Ethernet port (RJ-45)
- 6. Docking port
- 7. Power connector



Overview



- 1. Accessory battery connector
- EasyAccess panel 2.
- EasyAccess panel release latch 3.
- * Supports full-size 2FF (mini-SIM card)

- Security screw Vents (2) SIM slot * 4.

Overview

At a Glance

- Windows 10 versions, Windows 8 versions, Windows 7 versions, Ubuntu Linux or FreeDOS 2.0
- Magnesium and aluminum chassis, HP DuraFinish, HP DisplaySafe frame, HP duraKeys, precision aluminum drop hinge, aluminum palm rest
- 4-step Soft-touch paint process
- Patent-pending Drop-jaw Ethernet port
- EasyAccess door to quickly access most components for easy serviceability
- Full-sized spill-resistant keyboard; optional back-lit keyboard keeps you productive in low-light settings
- Choice of 5th Generation Intel[®] Core i7, i5 and i3 processors
- Memory options up to 16 GB
- Weight starting at 3.40 lbs/1.55 kg
- Storage options up to 1 TB Hard Drives, 512 GB Solid State Drives, or 256GB PCIe Solid State Drive
- M.2 32GB Flash Cache for Intel Smart Response Technology installed in the factory
- M.2 120GB Solid State Drive & 256GB PCIe Solid State Drive can be configured as primary storage or combined with a SATA drive for dual storage performance
- Integrated Intel® HD Graphics 5500 or AMD Radeon R7 M260X discrete graphics with 1 GB dedicated GDDR5 video memory
- Choice of Touch or Non Touch 14" diagonal displays
- Easily hot dock with the 2013 UltraSlim Docking Station
- DisplayPort for high resolution support
- Touchpad with scroll zone, on/off button with LED indicator
- Enhanced security features including HP Sure Start self-healing BIOS, HP Client Security and optional HP Fingerprint Reader
- Optional HD webcam with dual-microphone array for video conferencing
- HD Audio with DTS Studio Sound optimized for high fidelity audio
- · Wireless and speaker mute buttons
- Supports a broad range of wireless LAN and wireless WAN options, including 4G LTE, for connectivity on the go.
- UEFI BIOS Compliant with 2.3.1 UEFI Specification

NOTE: See important legal disclosures for all listed specs in their respective features sections.



HP EliteBook 840 G2 Notebook PC



Overview



Features

PRODUCT NAME

HP EliteBook 840 G2 Notebook PC

OPERATING SYSTEM

Preinstalled

Web-only Support

Windows 10 Pro 64* Windows 10 Home 64* Windows 8.1 Pro 64* Windows 8.1 64*

Windows 7 Professional 64 (available through downgrade rights from Windows 10 Pro)***

Windows 7 Professional 32 (available through downgrade rights from Windows 10 Pro)***

Windows 7 Professional 64 (available through downgrade rights form Windows 8.1 Pro)**

Windows 7 Professional 32 (available through downgrade

rights form Windows 8.1 Pro)**
Windows 7 Professional 64*
Windows 7 Professional 32*

Ubuntu Linux FreeDOS 2.0

Windows 10 Pro 64*
Windows 10 Home 64*
Windows 10 Enterprise 64*

Windows 8.1 64*
Windows 8.1 Pro 64*
Windows 8.1 Enterprise 64*

Windows 7 Professional 64 (available through downgrade rights from Windows 10 Pro)***

Windows 7 Professional 32 (available through downgrade rights from Windows 10 Pro)***

Windows 7 Professional 64 (available through downgrade rights form Windows 8.1 Pro)**

Windows 7 Professional 32 (available through downgrade

rights form Windows 8.1 Pro)**
Windows 7 Professional 64*
Windows 7 Professional 32*
Windows 7 Enterprise 64*

Windows 7 Enterprise 32*

^{***}This system is preinstalled with Windows 7 Professional software and also comes with a license and media for Windows 10 Pro software. You may only use one version of the Windows software at a time. Switching between versions will require you to uninstall one version and install the other version. You must back up all data (files, photos, etc.) before uninstalling and installing operating systems to avoid loss of your data.



^{*} Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.microsoft.com

^{**} This system is preinstalled with Windows 7 Professinal software and also comes with a license and media for Windows 8 Pro software. You may only use one version of the Windows software at a time. Switching between versions will require you to uninstall one version and install the other version. You must back up all data (files, photos, etc.) before uninstalling and installing operating systems to avoid loss of your data.

Features

PROCESSOR

- 5th Generation Intel® Core i3-5010U 2.1 GHz 3-MB L3 Cache, 15W
- 5th Generation Intel® Core i5-5200U 2.2 GHz (max turbo frequency 2.7-GHz), 3 MB L3 cache, 15W
- 5th Generation Intel® Core i5-5300U 2.3 GHz (max turbo frequency 2.9-GHz), 3 MB L3 Cache, 15W
- 5th Generation Intel® Core i7-5500U 2.4 GHz (max turbo frequency 3.0-GHz), 4 MB L3 Cache, 15W
- 5th Generation Intel® Core i7-5600U 2.6 GHz (max turbo frequency 3.2-GHz), 4 MB L3 Cache, 15W
- * Multi-Core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. 64-bit computing on Intel[®] architecture requires a computer system with a processor, chipset, BIOS, operating system, device drivers, and applications enabled for Inte 64 architecture. Processors will not operate (including 32-bit operation) without an Intel[®] 64 architecture-enabled BIOS. Performance will vary depending on your hardware and software configurations. Intel's numbering is not a measurement of higher performance.
- ** Not available with Intel iAMT (*Not available with vPro)

NOTE: Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.

Intel Turbo Boost Technology*

Intel Turbo Boost is a feature that speeds up the CPU for a short time. It is similar to overclocking the processor, except within a framework provided by Intel. This feature provides additional performance and allows the computer to perform certain tasks more quickly. It also draws additional power and generates additional heat. Therefore, if Turbo Boost is used while powered from battery, it causes additional stress on the battery.

Using Turbo Boost while powered from battery might impact battery cycle life. Cycle life describes how long the battery will last before it needs to be replaced. A cycle refers to one complete charge/discharge cycle of the battery. Because Turbo Boost causes extra stress on the battery, it often shortens the lifetime of the battery.

HP decided not to enable Turbo Boost when powered from battery. This decision was based on the desire to give customers the greatest battery cycle life possible. Turbo Boost is enabled when powered from AC adapter.

Based on customer requests, HP will provide an option to enable Turbo Boost while powered from battery. For the 2013 platform, it will be an F10 option. Turbo Boost will be available for devices powered from battery by the end of the year. The additional performance might cause a slight reduction in battery cycle life, but will not void the battery warranty.

*Implementing Turbo Boost in F10 option is only allowed for batteries over 40WHr. Intel® Turbo Boost technology requires a PC with a processor with Intel Turbo Boost capability. Intel Turbo Boost performance varies depending on hardware, software and overall system configuration. See http://www.intel.com/technology/turboboost for more information.

CHIPSET

Chipset integrated with processor

Intel Core i5 with vPro/Core i7 with vPro technology capable



Features

Intel Core i5 with vPro and Core i7 with vPro technology is a selectable feature that is available on units configured with select processors, an Intel Centrino® Advanced-N or Ultimate-N WLAN module and a preinstalled Windows operating system. It provides advances in remote manageability, security, energy efficient performance, and wireless connectivity. Intel Active Management Technology 9.0 (iAMT) offers built-in manageability and proactive security for networked notebook PCs, even when they are powered off* or when the operating system is inoperable. It can help identify threats before they reach the network, isolate infected systems, and update PCs regardless of their power state.

*Requires a Windows operating system, network hardware and software, connection with a power source, and a direc (non-VPN) corporate network connection which is either cable or wireless LAN.

NOTE: Some functionality of this technology, such as Intel® Active management technology and Intel Virtualization technology, requires additional 3rd party software in order to run. Availability of future "virtual appliances" applications for Intel vPro technology is dependent on 3rd party software providers. Microsoft Windows required.

GRAPHICS

Integrated:

Intel® HD* Graphics 5500

Discrete

AMD Radeon R7 M260X, with 1 GB dedicated DDR5 video memory**

*HD content required to view HD images.

**AMD Dynamic Switchable Graphics technology requires an Intel processor, plus an AMD Radeon discrete graphics configuration and is not available on FreeDOS and Linux OS. With AMD Dynamic Switchable Graphics technology, fu enablement of all discrete graphics video and display features may not be supported on all systems (e.g. OpenGL applications will run on the integrated GPU or the APU as the case may be).

DISPLAY

Internal

Non Touch

14.0" diagonal LED-backlit HD anti-glare SVA flat (1366x768)

14.0" diagonal LED-backlit HD anti-glare SVA flat (1366x768) with camera

14.0" diagonal LED-backlit HD+ anti-glare SVA flat (1600x900)

14.0" diagonal LED-backlit HD+ anti-glare SVA flat (1600x900) with camera

14.0" diagonal LED-backlit FHD anti-glare UWA slim (1920x1080)

14.0" diagonal LED-backlit FHD anti-glare UWA slim (1920x1080) with camera

Touch

14.0" diagonal LED-backlit FHD UWA slim (1920x1080) with camera

Touch panel has chemically-strengthened Corning® Gorilla® Glass 3 top cover

External

Up to 32-bit per pixel color depth

VGA

Port supports resolutions up to 1920 x 1200 external resolution@75 Hz

DisplayPort

Supports resolutions up to 3840 x 2160 @ 60Hz. Supports Multi-Stream Transport (MST) where three displays can b daisy chained with digital displays through DisplayPort Only. The full resolution of each display will be limited as you reach 3 displays due to the bandwidth limitations with a maximum resolution of:

- 2560x1600@60Hz for 2 displays
- 1920x1200@60Hz for 3 displays



Features

Number of Displays supported

3 With Optional* UltraSlim Docking Station *Sold separately.

STORAGE AND DRIVES

Primary Storage Bay -

Hard Drives*

320 GB 7200rpm SATA Hard Drive

500 GB 7200rpm SATA Hard Drive

500 GB 7200rpm Self-Encrypting Drive

500 GB 5400 rpm Self Encrypting Drive (FIPS-140-2)

500 GB 5400rpm + 8GB NAND SATA Hybrid Hard Drive

1TB 7200rpm SATA Hard Drive

Solid State Drive*

120 GB M.2 Solid State Drive

128 GB SATA-3 MLC Solid State Drive

128 GB SATA-3 TLC Solid State Drive

180 GB SATA-3 MLC Solid State Drive

180 GB SATA-3 MLC Self-Encrypting Drive

240 GB SATA-3 MLC Solid State Drive

256 GB SATA-3 TLC Solid State Drive

256 GB SATA-3 MLC Self-Encrypting Drive

256 GB M.2 PCIe Solid State Drive

512 GB SATA-3 MLC Solid State Drive

512 GB SATA-3 TLC Solid State Drive

HP 3D DriveGuard (Windows only)

HP 3D DriveGuard mitigates the risk of hard drive failures, safeguarding your data when you are on the go by sensing sudden movement and protecting the hard drive. The hard drive is mounted directly to the notebook frame, reducing the transmission of shock to the hard drive.

*For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 16 GB (for Windows 7) and up to 30 GB (for Windows 8 and 10) of system disk is reserved for the system recovery software.

FLASH CACHE

32 GB M.2 (NGFF)

Optional 32 GB M.2 flash cache module support for Intel Smart Response Technology. Available only with standard non-SED hard drive and non-solid state drives.

MEMORY



Features

Standard

DDR3L-1600 (Transfer rates up to 1600 MT/s)

Two SODIMM slots supporting dual-channel memory

4 GB Total System Memory (4 GB x 1)

8 GB Total System Memory (4 GB x 2) (Not available with Windows 7 Professional 32)

8 GB Total System Memory (8 GB x 1)) (Not available with Windows 7 Professional 32)

16 GB Total System Memory (8 GB x 2)) (Not available with Windows 7 Professional 32)

Maximum

Upgradeable to 16 GB with optional 8 GB SODIMMs in slots 1 and 2*

Dual-channel

Maximized dual-channel performance requires SODIMMs of the same size and speed in both memory slots.

* Maximum memory capacities assume Windows 64-bit operating systems or Linux. With Windows 32-bit operating systems, memory above 3 GB may not all be available due to system resource requirements.

NOTE: Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.

NETWORKING/COMMUNICATIONS

Wireless

Support for a broad range of secure, integrated wireless LAN and wireless WAN options featuring support for the lates industry standards. Broadband Wireless (WWAN) requires a Windows operating system and is available in select countries as a standard, factory configurable feature only. Integrated Bluetooth is also available (factory configurable only) and can be combined with any of the supported wireless LAN and wireless WAN options.

Broadband Wireless (WWAN)*

HP It4112 LTE/HSPA+ Qualcomm® Gobi 4G Module

HP It4211 LTE/EV-DO/HSPA+ Qualcomm® Gobi 4G Module**

HP hs3110 HSPA+ Mobile Broadband Module

* WWAN is an optional feature sold separately or as an add on feature. WWAN connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors.

**4G LTE WWAN is an optional feature, not available on all products, in all regions and requires separately purchased service contract. Check with service provider for coverage and availability. Connection speeds will vary due to location, environment, network conditions, and other factors.

Wireless LAN (WLAN)*

Intel® Dual Band Wireless-AC 7265 802.11 ac (2X2) Wi-Fi + Bluetooth®

Intel® Dual Band Wireless-7265AN 802.11 a/b/g/n (2X2) Wi-Fi + Bluetooth®

Intel® Dual Band Wireless-AC 3160 802.11 ac (1x1) Wi-Fi + Bluetooth®

*Wireless access point and Internet service is required and is not included.

Availability of public wireless access points limited.

Communications

Intel® I218LM Gigabit* Network Connection (10/100/1000 NIC)

* The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet and does not connote actual operating speed of 1 Gb/s. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

Optional Near Field Communication (NFC)

AUDIO/MULTIMEDIA



Features

Audio

HD Audio with DTS Studio Sound
2 Integrated stereo speakers
Integrated dual-microphone array; located in the display
Function keys for microphone mute, volume up, volume down
Stereo headphone/line out
Stereo microphone/line in

Webcam

Optional* 720p HD** webcam

- HD format (widescreen)
- Supports videoconferencing (non-HD) and still image capture
- High quality fixed focus lens
- Video capture at various resolutions up to 1280x720 resolution (720p) and up to 30fps
- M-JPEG compression supports higher frame rates for video capture and videoconferencing
- Improved low light sensitivity
- Improved dynamic range
- Skype-ready ***

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard

The HP spill-resistant keyboard is designed using a thin layer of Mylar film under the keyboard and includes an all-metal keyboard deck for greater rigidity, as well as HP DuraKeys. The 101/102-key compatible keyboard features a fulpitch key layout with desktop keyboard features, such as editing keys, both left and right control and alt keys, and function keys. US and International key layouts are available. Backlit keyboard available as an option.

Pointing Devices

Touchpad with scroll zone, on/off button with LED indicator, two-way scroll, two pick buttons

Buttons and Function Keys

Separate discrete buttons provide easy access to WLAN on/off and speaker mute. Function keys provide control of features including: standby mode, display brightness, external display, microphone mute, volume down, and volume up.

SOFTWARE AND SECURITY

Preinstalled Software with Windows Operating System

BIOS

HP BIOSphere¹

HP Sure Start

HP DriveLock | HP Automatic Drive Lock

HP BIOS Protection²

HP Disk Sanitizer3

HP SpareKey4

BIOS Update via Network

Master Boot Record Security

Power On Authentication

Pre-Boot Security

Secure Erase⁵

Hybrid Boot



^{*} Sold separately.

^{**} HD content required to view HD images.

^{***}Internet access required.

Features

Measured Boot

Secure Boot

Absolute Persistence Module⁶

- 1. Available only on business PCs with HP BIOS.
- 2. May require a manual recovery step if all copies of BIOS are compromised or deleted. BIOS adheres to NIST SP800-147.
- 3. For the use cases outlined in the DOD 5220.22-M Supplement. Does not support solid state drives.
- 4. Requires initial user set up.
- 5. For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88.
- 6. Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availabilit outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visi http://www.absolute.com/company/legal/agreements/computrace-agreement. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.

MultiMedia

CyberLink PowerDVD

CyberLink YouCam BE

Communication

HP Connection Manager with support for HP Mobile Connect (Windows 7 only)²

HP GPS and Location¹

HP Mobile Connect (Windows 8 only)²

HP Wireless Hotspot³ (Windows 8 only)

Intel WiDi Software⁴

HP Roaming Alert

Intel My WiFi and Wireless Drivers

HP Value Add Software

Getting Started with Windows 8

HP 3D DriveGuard (Windows required)

HP ePrint Driver (HP Exclusive)⁵

HP Hotkey Support

HP PageLift

HP Recovery Manager (Windows 7 only)

HP Support Assistant

HP Recovery Disc Creator (Windows 7 only)

UEFI System Diagnostics W8

3rd Partv

Adobe® Flash Player (Commercial)

Foxit PhantomPDF Express for HP

Bing Search

Skype⁶

Buy Office

NOTE: HP Recovery Manager enables fast recovery of the factory preinstalled image if the system becomes corrupted or if important system files are accidentally deleted. Up to 16 GB (for Windows 7) and 36 GB (for Windows 8) of system disk is reserved for the system recovery software.

- 1. GPS access requires an unobstructed path to multiple satellites. Performance may be affected if/when used inside of buildings, bridges or heavily congested metropolitan areas. Requires separately purchased GPS navigation software available from multiple GPS applications.
- 2. HP Mobile Connect is only available on selective devices with wwan. For geographical availability refer to http://www.hp.com/go/mobileconnect
- 3. The wireless hotspot application requires an active internet connection that is shared with the connecting devices. Wireless hotspot data usage may incur additional charges. Check with your service provider for plan details.
- 4. Integrated Intel Wi-Di feature is available on select configurations only and requires separately purchased projector, tv or computer monitor with an integrated or external Wi-Di receiver. External Wi-Di receivers connect to the projector, tv or computer monitor via a standard HDMI cable, also sold separately.
- 5. Requires an Internet connection to HP web-enabled printer and HP ePrint account registration (for a list of eligible



Features

printers, supported documents and image types and other HP ePrint details, see www.hp.com/go/businessmobileprinting..

6. Skype is not offered in China.

Manageability

HP Driver Packs *

HP SoftPaq Download Manager (SDM)

HP System Software Manager (SSM)*

HP BIOS Config Utility (BCU) *

HP Client Catalog / HP CIK for Microsoft SCCM *

LANDESK Management *

* Not preinstalled

For more information on HP Client Management Solutions refer to: http://www.hp.com/go/clientmanagement.

Standard Security Features

HP Client Security Manager (Windows only)

HP Device Access Manager

HP Drive Encryption¹

HP File Sanitizer²

Microsoft Security Essentials (Windows 7 only)³

TPM Embedded Security Chip 1.2

Security lock slot

Fingerprint Reader

Integrated Smart Card Reader

For more information on HP Client Security Software Suite, refer to http://www.hp.com/go/clientsecurity.

1. Requires Windows. Data is protected prior to Drive Encryption login. Turning the PC off or into hibernate logs out of Drive

Encryption and prevents data access.

- 2. For the use cases outlined in the DOD 5220.22-M Supplement. Supports standard Hard Drives. Initial setup required.
- 3. Opt in and internet connection required for updates.

POWER

Power Supply

HP 45W Smart AC Adapter

45W 2-prong 7.4mm DC jack AC Adapter (Only for Japan)

HP 65W Smart AC Adapter

HP 65W Smart EM AC Adapter (China and India only)

Power cord is configurable; either 3.2 feet or 6 feet (1.0 or 1.8 meter)

Total length including external AC adapter is 9.2 feet or 12 feet (2.86 or 3.66 meter).

Primary Battery

3-cell HP Long Life Polymer 24 WHr

3-cell HP Long Life Polymer/Prismatic 50 WHr

Secondary Battery

6-cell HP Long Life Polymer 60 WHr

Battery Life*



Features

Hardware details	Battery	With UMA Graphics	With Discrete Graphics
HDD	3-cell (50WHr)	Up to 12 hrs 15 mins	Up to 12 hrs 45 mins
SSD	3-cell (24Whr)	Up to 7 hrs 45 mins	Up to 7 hrs 15 mins
SSD	3-cell (50WHr)	Up to 16 hrs	Up to 15 hrs 15 mins
SSD	3-cell (50WHr) + Slice (60Whr)	Up to 35 hrs 30 mins	Up to 35 hrs 15 mins

^{*}Windows 7 MM07 battery life will vary depending on various factors including product model, configuration, loaded applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See http://www.bapco.com for additional details.

System Standby Time**

With UMA Graphics
Up to 180 hrs

With Discrete Graphics
Up to 171 hrs

The maximum capacity of the battery will naturally decrease with time and usage.

Power Conservation

Supports enhanced Intel SpeedStep technology (allows Battery Optimized Mode, Maximum Performance Mode, or Automatic mode)

AMD PowerPlay technology (discrete models)

Hibernation

Standby

ACPI compliance

WEIGHTS & DIMENSIONS

Weight

Non Touch

Starting at 3.40 lbs/1.55 kg

Weight will vary by configuration.

3-cell (24Whr) battery, HD panel, UMA, no FPR, one SODIMM, WLAN, lightest M.2 SSD primary storage module, no camera, no WWAN

Touch

Starting at 3.76 lbs/1.71 kg

Weight will vary by configuration.

3-cell (24Whr) battery, FHD Touch panel, UMA, no FPR, one SODIMM, WLAN, lightest M.2 SSD primary storage module, no camera, no WWAN

Dimensions (w x d x h)

Non Touch

13.35 x 9.33 x 0.83 in

33.9 x 23.7 x 2.10 cm (at front)

Touch

13.35 x 9.33 x 0.89 in

33.9 x 23.7 x 2.26 cm (at front)

PORTS/SLOTS



^{**}Standby life will vary depending on various factors including battery, Memory, CPU, EC and LAN chip.

Features

Ports

- (1) DisplayPort 1.2
- (1) USB 3.0 Charging Port
- (3) USB 3.0 Port
- (1) RJ-45 / Ethernet
- (1) Side Docking connector
- (1) Secondary battery connector
- (1) Headphone/Microphone Combo
- (1) AC Port

Expansion Slots

Media Card Reader

Supports SD, SDHC, SDXC

SERVICE AND SUPPORT

HP Services offers 3-year, 1-year and 90 day limited warranty options depending on country. Batteries have a default one year limited warranty except for Long Life batteries which will have same 1-year or 3-year limited warranty as the platform. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties.* To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/cpc.

NOTE: Certain restrictions and exclusions apply. Consult the HP Customer Support Center for details. http://h20000.www2.hp.com/bizsupport/TechSupport/ProductRoot.jsp

*HP Care Packs are sold separately. Service levels and response times for HP Care Services may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. Consult the HP Customer Support Center for details. http://h20000.www2.hp.com/bizsupport/TechSupport/ProductRoot.jsp



Technical Specifications

System Unit

Stand-Alone Power Requirements (AC	Nominal Operating Voltage Average Operating Power	19.5 V Windows 7 (64-bit)	Windows8 (64-bit)
Power)	Integrated graphics	4.75 W	4.26 W
,	Max Operating Power	Discrete < 90W	
		UMA < 65W	
Temperature	Operating	32° to 95° F (0° to 35° C) (not writing o	ptical)
		41° to 95° F (5° to 35° C) (writing optical	al)
	Non-operating	-4° to 140° F (-20° to 60° C)	
Relative Humidity	Operating	10% to 90%, non-condensing	
	Non-operating	5% to 95%, 101.6° F (38.7° C) maximu	ım wet bulb temperatı
Shock	Operating	40 G, 2 ms, half-sine	
	Non-operating	200 G, 2 ms, half-sine	
Random Vibration	Operating	0.75 grms	
	Non-operating	1.50 grms	
Altitude (unpressurized)	Operating	-50 to 10,000 ft (-15.24 to 3,048 m)	
	Non-operating	-50 to 40,000 ft (-15.24 to 12,192 m)	
Planned Industry	UL	Yes	
Standard	CSA	Yes	
Certifications	FCC Compliance	Yes	
	ENERGY STAR®	Select models*	
	EPEAT®	Registered Gold in United States**	
	ICES	Yes	
	Australia /	Yes	
	NZ A-Tick Compliance	.,	
	CCC	Yes	
	Japan VCCI Compliance	Yes	
	KC	Yes	
	BSMI	Yes	
	CE Marking Compliance	Yes	
	BNCI or BELUS	Yes	
	CIT GOST	Yes Yes	
	Saudi Arabian Compliance (ICCP)	Yes	
	SABS	Yes	
	UKRSERTCOMPUTER	Yes	

For accessibility information on HP products, please visit: http://www.hp.com/accessibility.

Displays Non-Touch



Technical Specifications

14" diagonal LEDbacklit HD anti-glare **SVA flat (1366 x 768)** **Outline Dimensions**

12.6 x 8.09 x 0.14 in (32.09 x 20.56 x 0.36 cm)

 $(W \times H \times D)$

Active Area 12.18 x 6.85 in (30.94 x 17.395 cm)

Weight 0.71 lb (320g) (max) **Diagonal Size** 14.0 in (35.6cm)

Contrast Ratio 300:1 (min) Refresh Rate 60 Hz

Brightness 200 nit (typical)

Format 1366 x 768 (HD) **Pixel Resolution** Configuration **RGB Stripe**

Interface eDP 1.2 (1 lane)

LCD Mode ΤN PPI 125 ppi

Viewing Angle SVA 40/40/15/30 (Left/Right/Down/Up)

14" diagonal LEDbacklit HD+ anti-glare **SVA flat (1600 x 900)**

Outline Dimensions

12.6 x 8.09 x 0.14 in (32.09 x 20.56 x 0.36 cm)

 $(W \times H \times D)$

Active Area 12.19 x 6.86 in (30.96 x 17.415 cm)

Weight 0.72 lb (325 g) (max) **Diagonal Size** 14.0 in (35.6cm)

Contrast Ratio 300:1 (min) Refresh Rate 60 Hz

Brightness 250 nit (typical)

Format 1600 x 900 (HD+) **Pixel Resolution RGB Stripe**

Configuration

Interface eDP 1.2 (1 lane)

LCD Mode ΤN PPI 131 ppi

Viewing Angle SVA 40/40/15/30 (Left/Right/Down/Up)



Technical Specifications

14" diagonal LEDbacklit FHD anti-glare UWVA slim (1920 x 1080)

Outline Dimensions

 $(W \times H \times D)$

12.18 x 6.85 in (30.93 x 17.4 cm)

12.6 x 8.09 x 0.12 in (32.09 x 20.56 x 0.3 cm)

Active Area Weight

0.75 lb (340 g) (max)

Diagonal Size

14.0 in (35.6cm)

Contrast Ratio 600:1 (min) Refresh Rate 60 Hz

Brightness 300 nit (typical)

Format 1920 x 1080 (FHD) **Pixel Resolution**

Configuration Interface eDP 1.3+PSR (2 lane)

LCD Mode IPS/FFS/VA PPI 157 ppi

Viewing Angle UWVA 85/85/85/85 (Left/Right/Down/Up)

Touch

14" diagonal LEDbacklit FHD anti-glare UWVA slim (1920 x 1080)+touch

Outline Dimensions

12.6 x 8.09 x 0.12 in (32.09 x 20.56 x 0.3 cm)

RGB Stripe

 $(W \times H \times D)$

Active Area 12.18 x 6.85 in (30.93 x 17.4 cm)

Weight 0.75 lb (340 g) (max) **Diagonal Size** 14.0 in (35.6cm)

Touch enabled Yes **TSP Type** Capacitive

Touch point supported Min 5-point & Max 10-point for Win8

Contrast Ratio 600:1 (min) Refresh Rate 60 Hz

Brightness 300 nit (typical)

Format 1920 x 1080 (FHD) **Pixel Resolution**

Configuration **RGB Stripe**

Interface eDP 1.3+PSR (2 lane)

LCD Mode IPS/FFS/VA PPI 157 ppi

Viewing Angle UWVA 85/85/85/85 (Left/Right/Down/Up)

Storage and Drives



Technical Specifications

 320 GB* 7200 rpm SATA Drive Weight
 0.21 lbs (95 g)

 Hard Drive
 Capacity
 320 GB

 Height
 0.28 in (7 mm)

 Width
 2.75 in (69.85 mm)

 Interface
 ATA-8, SATA 3.0

Transfer Rate Synchronous 600 MB/s (Drive Capability)

(maximum)

Seek TimeSingle Track1.5 ms-2ms(typical reads, including settling)Average12 ms-13msMaximum18ms-22 ms

CacheUp to 32 MBRotational Speed7200 rpmLogical Blocks625,142,448

Operating Temperature 32° to 140° F (0° to 60° C) [case temp]

Features ATA Security; S.M.A.R.T. IV, NCQ, Ultra DMA

500 GB* 7200 rpm SATA Hard Drive

Drive Weight 0.20lbs(92g- 0.21 lbs (95g)

Capacity 500 GB

 Height
 0.28 in (7 mm)

 Width
 2.75 in (69.85 mm)

 Interface
 ATA-8, SATA 3.0

Transfer Rate Synchronous 600 MB/s (Drive Capability)

(maximum)

Seek TimeSingle Track1.5 ms-2ms(typical reads, including settling)Average12 ms-13msMaximum18ms-22 ms

Rotational Speed 7200 rpm Logical Blocks 976,773,168

Operating Temperature 32° to 140° F (0° to 60° C) [case temp]

Features ATA Security; S.M.A.R.T. IV, NCQ, Ultra DMA

500 GB* 7200 rpm SMART SATA II Self Encrypting Drive

 Drive Weight
 0.21 lbs (95g)

 Capacity
 500 GB

 Height
 0.28 in (7 mm)

 Width
 2.75 in (69.85 mm)

 Interface
 ATA-8, SATA 3.0

Transfer Rate Synchronous 300 MB/s (Drive Capability)

(maximum)

Seek TimeSingle Track2 ms(typical reads, including settling)Average13 msMaximum18 ms

Cache32 MBRotational Speed7200 rpmLogical Blocks976,773,168

Operating Temperature32° to 140° F (0° to 60° C) [case temp]

Features ATA Security; TCG OPAL v1.00



Technical Specifications

500 GB* 5400 rpm **Drive Weight** 0.21 lbs (95g) **SMART SATA II FIPS Capacity** 500 GB Self Encrypting Drive Height

0.28 in (7 mm) Width 2.75 in (69.85 mm) Interface ATA-8, SATA 3.0

Transfer Rate Synchronous 600 MB/s (Drive Capability)

(maximum)

Seek Time **Single Track** 1.5 ms (typical reads, including **Average** 12 ms settling) **Maximum** 22 ms

Cache 16 MB **Rotational Speed** 5400 rpm **Logical Blocks** 976,773,168

Operating Temperature 32° to 140° F (0° to 60° C) [case temp] **Features** ATA Security; TCG Opal 2.x, FIPS

0.25 lb (115 g) 1 TB* 7200 rpm **Drive Weight** Capacity 1 TB **SATA Hard Drive**

Height 0.37 in (9.5 mm)

Width 2.75 in (69.85 mm) Interface ATA-8, SATA 3.0

Transfer Rate Synchronous 600 MB/s (Drive Capability)

(maximum)

Seek Time Single Track 2 ms (typical reads, including Average 13 ms Maximum 15 ms settling)

Rotational Speed 7200 rpm **Logical Blocks** 1,953,525,168

32° to 140° F (0° to 60° C) [case temp] Operating

Temperature

Features ATA Security; S.M.A.R.T. IV, NCQ, Ultra DMA

500 GB 5400rpm + **8GB NAND SATA Hybrid Hard Drive**

95g **Drive Weight** 500GB Capacity Height 7_{mm} Width 70.1mm

ATA-8, SATA 3.0 Interface

Transfer Rate 600MB/s

5.6ms (Average Latency) **Seek Time**

(typical reads, including

settling)

5400rpm **Rotational Speed** 976,733,168 **Logical Blocks** 0-60 degree C **Operating Temperature**

ATA Security, S.M.A.R.T., NCQ, Ultra DMA **Features**



Technical Specifications

SATA 3 Gb/s 32 GB*. M.2 2242 Solid State **Drive**

Drive Weight 10 Grams Capacity 32 GB

Height 0.09 in (3.7 mm) Width 0.87 in (22 mm) Interface ATA-8, SATA 3.0

Performance Maximum Sequential **Maximum Sequential Write**

Up to 380 MB/s Up to 110 MB/s

Logical Blocks 62,533,296

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp] **Features** ATA Security; DIPM; TRIM; DEVSLP

SATA 3 Gb/s 120 GB*. M.2 2242 Solid State

Drive

Drive Weight 10 Grams 120 GB Capacity

Height 0.09 in (3.7 mm) Width 0.87 in (22 mm) Interface ATA-8, SATA 3.0

Performance Maximum Sequential **Maximum Sequential Write**

Read

Up to 540 MB/s Up to 480 MB/s

Logical Blocks 234,441,648

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp] **Features** ATA Security; DIPM; TRIM; DEVSLP

SATA 3 Gb/s 128 GB*, 2.5-inch MLC Solid State Drive

Drive Weight 78- Grams Capacity 128 GB

Height 0.28 in (7 mm) Width 2.75 in (69.85 mm) Interface ATA-8, SATA 3.0

Performance Maximum Sequential **Maximum Sequential Write**

Read

Up to 550 MB/s Up to 350 MB/s

Logical Blocks 250,069,680

Operating Temperature32° to 158°F (0° to 70°C) [ambient temp] **Features** ATA Security; DIPM; TRIM; DEVSLP

SATA 3 Gb/s 128 GB*, **Drive Weight** 78 Grams

2.5-inch TLC Solid State

Drive

Capacity 128 GB Height 0.28 in (7 mm) Width 2.75 in (69.85 mm) Interface ATA-8, SATA 3.0

Performance Maximum Sequential Maximum Sequential Write

Read

Up to 520 MB/s Up to 140 MB/s

250,069,680 **Logical Blocks**

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp] **Features** ATA Security; DIPM; TRIM; DEVSLP



Technical Specifications

SATA 3 Gb/s 180 GB*, 2.5-inch SATA Solid **State Drive**

Drive Weight 78 Grams Capacity 180 GB Height

0.28 in (7 mm) Width 2.75 in (69.85 mm) Interface ATA-8, SATA 3.0

Performance Maximum Sequential **Maximum Sequential Write**

Read

Up to 540 MB/s Up to 490 MB/s

Logical Blocks 351,651,888

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp] **Features** ATA Security; DIPM; TRIM; DEVSLP

SATA 3 Gb/s 180 GB*. 2.5-inch SATA SED **Solid State Drive**

Drive Weight Up to 78 Grams

Capacity 180 GB

Height 0.28 in (7 mm) Width 2.75 in (69.85 mm) Interface ATA-8, SATA 3.0

Performance Maximum Sequential **Maximum Sequential Write**

Read

Up to 540 MB/s Up to 490 MB/s

Logical Blocks 351.651.888

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; DIPM; TRIM; DEVSLP; TCG Opal 1x

SATA 3 Gb/s 240 GB*, 2.5-inch Solid State

Drive

Drive Weight 78 Grams Capacity 240 GB Heiaht 0.28 in (7 mm) Width 2.75 in (69.85 mm) Interface ATA-8, SATA 3.0

Performance Maximum Sequential **Maximum Sequential Write**

Read

Up to 540 MB/s Up to 490 MB/s

Logical Blocks 468,862,128

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp] **Features** ATA Security; DIPM; TRIM; DEVSLP

SATA 3 Gb/s 256 GB*, 2.5-inch Solid State **Drive**

Drive Weight 78 Grams Capacity 256 GB Height

0.28 in (7 mm) Width 2.75 in (69.85 mm) Interface ATA8, SATA 3.0

Performance Maximum Sequential **Maximum Sequential Write**

Read

Up to 520 MB/s Up to 280 MB/s

Logical Blocks 500,118,192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; TCG Opal 2.x; DIPM; TRIM; DEVSLP



Technical Specifications

SATA 3 Gb/s 256 GB*,

Solid State Drive

Drive Weight 78 Grams 2.5-inch Self Encrypting Capacity 256 GB

Height 0.28 in (7 mm) Width 2.75 in (69.85 mm) Interface ATA8, SATA 3.0

Maximum Sequential **Performance Maximum Sequential Write**

Read

Up to 550 MB/s Up to 500 MB/s

Logical Blocks 500,118,192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; TCG Opal 2.x; DIPM; TRIM; DEVSLP

SATA 3 Gb/s 256 GB*, 2.5-inch M2 PCIe Solid Capacity

State Drive

Drive Weight 10 Grams 256 GB

Height 0.24 in (60 mm) Width 0.87 in (22 mm) Interface ATA-8, PCIe 2.0

Performance Maximum Sequential Maximum Sequential Write

Read

Up to 730 MB/s 620 MB/s

Logical Blocks 500,118,192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp] **Features** ATA Security; DIPM; TRIM; DEVSLP

SATA 3 Gb/s 512 GB*, 2.5-inch Solid State

Drive

Drive Weight 78 Grams Capacity 512 GB

Height 0.28 in (7 mm) Width 2.75 in (69.85 mm) Interface ATA-8, SATA 3.0

Performance Maximum Sequential Maximum Sequential Write

Read

Up to 550 MB/s Up to 550 MB/s

Logical Blocks 1,000,215,216

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp] **Features** ATA Security; DIPM; TRIM; DEVSLP

Networking/Communications

Broadband Wireless (WWAN)



Technical Specifications

HP It4112 LTE/HSPA+ Gobi 4G Module**

bands

Technology/Operating LTE FDD all bands with diversity: 2100 MHz (Band I), 1900 MHz (Band II), 1800 MHz (Band III), 850 MHz (Band V), 2600 MHz (Band VII), 900

MHz (Band VIII), 800 MHz (Band XX, DD800)

WCDMA/HSDPA/HSUPA/HSPA+ all bands with diversity: 2100 MHz (Band I), 1900 MHz (Band II), 800 MHz (Band V), 900 MHz (Band VIII) GSM/GPRS/EDGE: 1900 MHz (Band II), 1800 MHz (Band III), 850 MHz

(Band V), 900 MHz (Band VIII)

Wireless protocol

standards

3GPP Release 8 LTE Specification

WCDMA R99, 3GPP Release 5, 6 and 7 UMTS Specification

Wireless parametric

standards

Complies with 3GPP specifications Release 8 for LTE

Maximum data rates LTE (Category 3): 100 Mbps (Download), 50Mbps (Upload)

> DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21.6 Mbps (Download), 5.76 Mbps (Upload) EDGE: 236.8 kbps (Download), 236.8 kbps (Upload) GPRS: 85.6 kbps(Download), 85.6 kbps (Upload)

GPS Standalone

GPS bands 1575.42 MHz (± 1.023 MHz), GLONASS 1596-1607MHz

Maximum output powerLTE: +23 dBm (+/- 2 dBm)

WCDMA: +23.5 dBm (+/- 1 dBm) GPRS Band II, III: +29.5 dBm (+/- 1 dBm) GPRS Band V, VIII: +32.5 dBm (+/- 1 dBm) EGPRS Band II, III: +26.5 dBM (+/-1.5 dBm) EGPRS Band V, VIII: +27.5 dBM (+/-1.5 dBm)

Maximum power consumption

LTE: 1,200 mA (peak); <900 mA (average) WCDMA: 1,100 mA (peak); <800 mA (average) EGPRS: 2,800 mA (peak); <700 mA (average)

Power consumption,

sleep mode

3 mA

Power management

Antenna type

USB selective suspend, Integrated notebook wireless button Dual high efficiency multi-band antennae with spatial diversity

Form Factor M.2, USB 2.0 interface

Weight 6 g

Dimensions

42 mm × 30 mm × 2.3 mm

(Length x Width x

Thickness)

Voltage, Operating 3.135 V to 4.4 V (3.3 V +1.1V/-0.165V)

Temperature, operating 14° to 131° F (-10° to 55° C)

(from TIA/EIA/IS-98-D)

Temperature, nonoperating, 96 hours (from MIL-STD 202 Method 108)

-40° to 185° F (-40° to 85° C)

Humidity, non-

95% relative humidity for 48 hours @ 185° F (85° C) (non-condensing)

operating

LED Off - Radio Off; Solid LED On - Radio On LED activity

* 4G LTE not available on all products, in all regions and only available on products featuring Intel processors. WWAN use requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors.



Technical Specifications

HP It4211 LTE/EV-DO/HSPA+ Gobi 4G

Module

Technology/Operating

bands

LTE: 1900 (Band 2), 1700/2100 (Band 4), 850 (Band 5), 700 (Band 13 upper SMH), 700

(Band 17 lower SMH), 1900 MHz (Band 25, extended PCS) MHz

HSPA+: 2100 (Band 1), 1900 (Band 2), 1700/2100 (Band 4), 850 (Band 5), 900 (Band 8)

MHz

E-GPRS: 1900 (Band 2), 1800 (Band 3), 850 (Band 5), 900 (Band 8) MHz

EV-DO: 800 (BC0), 1900 (BC1) MHz

Wireless protocol

standards

3GPP Release 8 LTE Specification

WCDMA R99, 3GPP Release 5, 6 and 7 UMTS Specification

E-GPRS: Class B, Multi-slot class 33, coding schemes CS1 - CS4 and MSC1 - MSC9

EVDO Release 0 and Release A

GPS Standalone, A-GPS

GPS bands 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz

Maximum data rates LTE: 100 Mbps (Download), 50 Mbps (Upload)

DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21.6 Mbps (Download), 5.76 Mbps (Upload) EDGE: 236.8 kbps (Download), 236.8 kbps (Upload) GPRS: 85.6 kbps(Download), 85.6 kbps (Upload)

CDMA 1x: DL 153.6 kbps/UL 153.6 kbps

EVDO Rev.A: DL 3.1 Mbps/UL 1.8 Mbps

Maximum output power LTE: 23 dBm

HSPA+: 23.5 dBm

E-GPRS 1900/1800: 26.5 dBM E-GPRS 900/850: 27.5 dBM GPRS 1900/1800: 29.5 dBm GPRS 900/850: 32.5 dBm CDMA/EVDO: 24dBm

Maximum power

consumption

LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average) E-GPRS: 2,800 mA (peak); 700 mA (average)

EVDO: 1000mA (peak); 720mA (average)

Form Factor M.2, 3042-S3 Key B

Weight 6 g

weight 0

Dimensions 1.65 x 1.18 x 0.09 in (42 x 30 x 2.3 mm)

(Length x Width x

Thickness)



Technical Specifications

HP hs3110 HSPA+ Mobile Broadband

Module

Technology/Operating

bands

HSPA+: 2100 (Band 1), 1900 (Band 2), 850 (Band 5), 700 (Band 17) MHz E-GPRS: 1900 (Band 2), 1800 (Band 3), 850 (Band 5), 900 (Band 8) MHz

Wireless protocol

standards

WCDMA R99, 3GPP Release 5, 6 and 7 UMTS Specification

E-GPRS: Class B, Multi-slot class 33, coding schemes CS1 - CS4 and MSC1 - MSC9

GPS Standalone, A-GPS

GPS bands Maximum data rates 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21.6 Mbps (Download), 5.76 Mbps (Upload) EDGE: 236.8 kbps (Download), 236.8 kbps (Upload) GPRS: 85.6 kbps(Download), 85.6 kbps (Upload)

Maximum output power HSPA+: 23.5 dBm

E-GPRS 1900/1800: 26.5 dBM E-GPRS 900/850: 27.5 dBM GPRS 1900/1800: 29.5 dBm GPRS 900/850: 32.5 dBm

Maximum power consumption

HSPA+: 1,100 mA (peak); 800 mA (average) E-GPRS: 2,800 mA (peak); 700 mA (average)

Form Factor M.2, 3042-S3 Key B

Weight 6g

Dimensions

1.65 x 1.18 x 0.09 in (42 x 30 x 2.3 mm)

(Length x Width x Thickness)

Wireless LAN

Intel® 802.11 a/b/g/n ac (2X2) + Bluetooth®

Wireless LAN
Standards

IEEE 802.11a
IEEE 802.11b
IEEE 802.11n
IEEE 802.11n
IEEE 802.11ac
Wi-Fi certified
802.11b/g/n

• 2.402 - 2.482 GHz

Note:

The FCC has declared as of January 1, 2015 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

802.11a

- 4.9 4.95 GHz (Japan)
- 5.15 5.25 GHz
- 5.25 5.35 GHz
- 5.47 5.725 GHz
- 5.825 5.850 GHz

Note:

Indonesia only supports 5.725 - 5.825 GHz (CH149 - CH161)



Technical Specifications

Data Rates 802.11b: 1, 2, 5.5, 11 Mbps

802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)

802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and

80MHz)

Modulation Direct Sequence Spread Spectrum

BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM

Security1

• IEEE and WiFi compliant 64 / 128 bit WEP encryption

for a/b/g mode only

AES-CCMP: 128 bit in hardware

• 802.1x authentication

• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

WPA2 certification

• IEEE 802.11i

 Cisco Certified Extensions, all versions through CCX4 and CCX Lite

WAPI

Network Architecture

Models Roaming Output Power² Ad-hoc (Peer to Peer)

Infrastructure (Access Point Required)

IEEE 802.11 compliant roaming between access points

802.11b : +16dBm minimum 802.11g : +14dBm minimum 802.11a : +14dBm minimum

802.11n HT20(2.4GHz): +13dBm minimum 802.11n HT40(2.4GHz): +13dBm minimum 802.11n HT20(5GHz): +12dBm minimum 802.11n HT40(5GHz): +12dBm minimum 802.11ac 80MHz(5GHz): +11dBm minimum

Power Consumption Transmit: 2.0 W (max) Receive: 1.6 W (max)

Idle mode (PSP): 180 mW (WLAN Associated)

Idle mode: 60 mW (WLAN unassociated)

Radio disabled: 30 mW

Power Management ACPI and PCI Express compliant power management

802.11 compliant power saving mode

Receiver Sensitivity³

802.11b, 1Mbps: -94dBm maximum 802.11b, 11Mbps: -86dBm maximum 802.11g, 6Mbps: -88dBm maximum 802.11g, 54Mbps: -74dBm maximum 802.11a, 6Mbps: -86dBm maximum 802.11a, 54Mbps: -72dBm maximum 802.11n, MCS07: -69dBm maximum 802.11n, MCS15: -66dBm maximum 802.11ac, 1SS, MCS-0: -86dBm maximum 802.11ac, 1SS, MCS-9: -61dBm maximum

802.11ac, 2SS, MCS-0 : -83dBm maximum 802.11ac, 2SS, MCS-9 : -58dBm maximum

Antenna type High efficiency antenna with spatial diversity, mounted in the display

enciosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth

communications

Form Factor PCI-Express M.2 MiniCard Type 2230 : 2.3 x 22.0 x 30.0 mm

Or

Type 1630 : 2.3 x 16.0 x 30.0 mm



Technical Specifications

Weight Type 2230 : 2.8g

Or

Type 1630 : 2g

Operating Voltage 3.3v +/- 9%

 Temperature
 Operating Non-operating
 14° to 158° F (-10° to 70° C)

 -40° to 176° F (-40° to 80° C)

Humidity Operating 10% to 90% (non-condensing)
Non-operating 5% to 95% (non-condensing)

 Altitude
 Operating Non-operating
 0 to 10,000 ft (3,048 m)

 0 to 50,000 ft (15,240 m)

LED Activity

LED Amber - Radio OFF; LED White - Radio ON

1. Check latest software/driver release for updates on supported security features.

Maximum output power may vary by country according to local regulations.
 Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

HP Integrated Module with Bluetooth 4.0+EDR Wireless Technology

Bluetooth Specification 4.0+EDR Compliant **Frequency Band** 2402 to 2480 MHz

Number of Available Channels 79 (1 MHz) available channels

Data Rates and Throughput 3 Mbps data rate; throughput up to 2.17 Mbps

8DPSK

Synchronous Connection Oriented links up to 3, 64 kbps, voice

channels

Asynchronous Connection Less links 2178.1 kbps/177.1 kbps

asymmetric or 1306.9 kbps symmetric

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth c

with a maximum transmit power of +4 dBm for BR and EDR.

-80 dBm

 Modulation
 0.01% BER
 0.001% BER

 GFSK
 -80 dBm
 -70 dBm

 π/4-DQPSK
 -80 dBm
 -70 dBm

Power Consumption Peak (Tx) 330 mW Peak (Rx) 230 mW

Selective Suspend 17 mW

Range Up to 33 ft (10 m)
Electrical Interface USB 2.0 compliant

Bluetooth Software Supported

Microsoft Windows Bluetooth Software

Link Topology
Electrical Interface

Bluetooth Software Supported

Security

Point to Point, Multipoint Pico Nets up to 7 slaves

Full support of Bluetooth Security Provisions

Power Management Microsoft Windows ACPI, and USB Bus Support

Power Management Self-configurable to optimize power conservation in all operating

Certifications modes, including Standby, Hold, Park, and Sniff

Security All necessary regulatory approvals for supported countries, inclu

Certifications FCC (47 CFR) Part 15C, Section 15.247 & 15.249

Bluetooth Profiles Supported Power Management

Power ManagementETS 300 328, ETS 300 826CertificationsLow Voltage Directive IEC950

Low Voltage Directive IEC950 UL, CSA, and CE Mark

Serial Port Profile (SPP)¹

Service Discovery Application Profile (SDAP)

Dial-Up Networking (DUN)^{1,2}

Generic Object Exchange Profile (GOEP)^{1,2}

Object Push Profile (OPP)^{1,2}
File Transfer Profile (FTP)

Certifications Synchronization Profile (SYNC)



-70 dBm

Technical Specifications

Bluetooth Profiles Supported Hard Copy Cable Replacement (HCRP)^{1,2}

Personal Area Networking Profile (PAN)^{1,2} Human Interface Device Profile (HID)^{1,2}

FAX Profile (FAX)

Basic Imaging Profile (BIP)² Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)

Intel® 802.11 a/b/g/n (2X2) +Bluetooth®

Wireless LAN IEEE 802.11a Standards IEEE 802.11b IEEE 802.11g IEEE 802.11n

Interoperability Wi-Fi certified Frequency Band 802.11b/g/n

• 2.402 - 2.482 GHz

Note:

The FCC has declared as of January 1, 2015 products that ut passive scanning on channel 12/13 and are capable of transmust fully comply with requirements of 15.247 or otherwise d those channels.

802.11a

• 4.9 - 4.95 GHz (Japan)

• 5.15 - 5.25 GHz

• 5.25 - 5.35 GHz

• 5.47 - 5.725 GHz

• 5.825 - 5.850 GHz

Note:

Indonesia only supports 5.725 - 5.825 GHz (CH149 - CH16

Antenna Structure 2 transmit; 2 receive (2x2)

Data Rates 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps

802.11b: 1, 2, 5.5, 11 Mbps

802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps

802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)

Modulation Direct Sequence Spread Spectrum

CCK, BPSK, QPSK, 16-QAM, 64-QAM

Security¹

• IEEE and WiFi compliant 64 / 12

 IEEE and WiFi compliant 64 / 128 bit WEP encryption for mode only

AES-CCMP: 128 bit in hardware

• 802.1x authentication

WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and

WPA2 certification

IEEE 802.11i

 Cisco Certified Extensions, all versions through CCX4 and Lite

WAPI

Sub-channels Multinational support with frequency bands and channels compl

local regulations.

Network Architecture Ad-hoc (Peer to Peer)

Models Infrastructure (Access Point Required)
Roaming IEEE 802.11 compliant roaming between

RoamingIEEE 802.11 compliant roaming between band Access Points **Output Power**²

■ 802.11b: +16dBm minimum

802.11b: +16dBm minimum802.11g: +14dBm minimum



Technical Specifications

• 802.11a: +14dBm minimum

802.11n HT20(2.4GHz): +13dBm minimum
802.11n HT40(2.4GHz): +13dBm minimum
802.11n HT20(5GHz): +12dBm minimum
802.11n HT40(5GHz): +12dBm minimum

Power Consumption Transmit: 2.0 W (max)

Receive: 1.6 W (max)

Idle mode (PSP): 180 mW (WLAN Associated)
Idle mode: 60 mW (WLAN unassociated)

Radio disabled: 30 mW

Power Management ACPI and PCI Express compliant power management

802.11 compliant power saving mode

Receiver Sensitivity⁴ 802.11b, 1Mbps : -94dBm maximum

802.11b, 11Mbps: -86dBm maximum 802.11g, 6Mbps: -88dBm maximum 802.11g, 54Mbps: -74dBm maximum 802.11a, 6Mbps: -86dBm maximum 802.11a, 54Mbps: -72dBm maximum 802.11n, MCS07: -69dBm maximum 802.11n, MCS15: -66dBm maximum

Antenna type High efficiency antenna with spatial diversity, mounted in the dis

enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the

card to support WLAN MIMO and Bluetooth communications

Form Factor PCI-Express M.2 MiniCard

Dimensions Type 2230 : 2.3 x 22.0 x 30.0 mm

Or

Type 1630: 2.3 x 16.0 x 30.0 mm

Weight Type 2230 : 2.8g

Or

Type 1630 : 2g

Operating Voltage 3.3v +/- 9%

Temperature Operating 14° to 158° F (-10° to 7

Non-operating -40° to 176° F (-40° to

C)

Humidity Operating 10% to 90% (non-

Non-operating condensing)

5% to 95% (noncondensing)

Altitude Operating 0 to 10,000 ft (3,048 m

Non-operating 0 to 50,000 ft (15,240 r

LED Activity LED Amber - Radio OFF; LED White - Radio ON

- 1. Check latest software/driver release for updates on supported security features.
- 2. Maximum output power may vary by country according to local regulations.
- 3. In Power Save Polling mode and on battery power.
- 4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CCK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).
- 5. WLAN supplier's client utility is required for Cisco Compatible Extensions support with Microsoft Windows XP. WLAN may also be compatible with certain third-party software supplicants. WLAN supplier IHV extensions required for Cisco Compatible Extensions support for Microsoft Windows V



Technical Specifications

HP Integrated Module with Bluetooth 4.0+EDR Wireless Technology

Bluetooth Specification 4.0+EDR Compliant Frequency Band 2402 to 2480 MHz

Number of Available Channels 79 (1 MHz) available channels

Data Rates and Throughput 3 Mbps data rate; throughput up to 2.17 Mbps

Synchronous Connection Oriented links up to 3, 64 kbps, voice

channels

Asynchronous Connection Less links 2178.1 kbps/177.1 kbps

asymmetric or 1306.9 kbps symmetric

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth c

with a maximum transmit power of +4 dBm for BR and EDR.

Receiver Sensitivity

 Modulation
 0.01% BER
 0.001% BER

 GFSK
 -80 dBm
 -70 dBm

 π/4-DQPSK
 -80 dBm
 -70 dBm

 8DPSK
 -80 dBm
 -70 dBm

Power Consumption Peak (Tx) 330 mW

Peak (Rx) 230 mW

Selective Suspend 17 mW

Range Up to 33 ft (10 m)
Electrical Interface USB 2.0 compliant

Bluetooth Software Supported

Link Topology

Microsoft Windows Bluetooth Software

Electrical Interface
Bluetooth Software Supported

Security

Point to Point, Multipoint Pico Nets up to 7 slaves

Full support of Bluetooth Security Provisions

Power Management Microsoft Windows ACPI, and USB Bus Support

Power Management Self-configurable to optimize power conservation in all operating

Certifications modes, including Standby, Hold, Park, and Sniff

Security All necessary regulatory approvals for supported countries, inclu

Certifications FCC (47 CFR) Part 15C, Section 15.247 & 15.249

Bluetooth Profiles Supported

Power Management

Certifications Low Voltage Directive IEC950

UL, CSA, and CE Mark Serial Port Profile (SPP)¹

ETS 300 328, ETS 300 826

Service Discovery Application Profile (SDAP)

Dial-Up Networking (DUN)^{1,2}

Generic Object Exchange Profile (GOEP)^{1,2}

Object Push Profile (OPP)^{1,2}
File Transfer Profile (FTP)

Certifications Synchronization Profile (SYNC)

Bluetooth Profiles Supported Hard Copy Cable Replacement (HCRP)^{1,2} Personal Area Networking Profile (PAN)^{1,2}

Human Interface Device Profile (PAN)^{1,2}

FAX Profile (FAX)

Basic Imaging Profile (BIP)² Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)

Intel® 802.11 ac (2x2) WiFi + Bluetooth® 4.0 combo (Indonesia only)

Wireless LAN

IEEE 802.11a



Technical Specifications

Standards IEEE 802.11b

IEEE 802.11g IEEE 802.11n

Interoperability Frequency Band

Data Rates

IEEE 802.11ac Wi-Fi certified 802.11b/g/n

• 2.402 - 2.482 GHz

Note:

The FCC has declared as of January 1, 2015 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

802.11a

• 4.9 - 4.95 GHz (Japan)

• 5.15 - 5.25 GHz

• 5.25 - 5.35 GHz

5.47 - 5.725 GHz

• 5.825 - 5.850 GHz

Note:

Indonesia only supports 5.725 - 5.825 GHz (CH149 - CH161)

802.11b: 1, 2, 5.5, 11 Mbps

802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)

802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and

80MHz)

Modulation Direct Sequence Spread Spectrum

BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM

Security1 • IEEE and WiFi compliant 64 / 128 l

 IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only

• AES-CCMP: 128 bit in hardware

802.1x authentication

 WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

WPA2 certification

• IEEE 802.11i

 Cisco Certified Extensions, all versions through CCX4 and CCX Lite

WAPI

Network Architecture

Models Roaming Output Power² Ad-hoc (Peer to Peer)

Infrastructure (Access Point Required)

IEEE 802.11 compliant roaming between access points

802.11b : +16dBm minimum 802.11g : +14dBm minimum 802.11a : +14dBm minimum

802.11n HT20(2.4GHz): +13dBm minimum 802.11n HT40(2.4GHz): +13dBm minimum 802.11n HT20(5GHz): +12dBm minimum 802.11n HT40(5GHz): +12dBm minimum 802.11ac 80MHz(5GHz): +11dBm minimum



Technical Specifications

Power Consumption Transmit: 2.0 W (max)

Receive: 1.6 W (max)

Idle mode (PSP): 180 mW (WLAN Associated)
Idle mode: 60 mW (WLAN unassociated)

Radio disabled: 30 mW

Power Management ACPI and PCI Express compliant power management

802.11 compliant power saving mode

Receiver Sensitivity³ 802.11b, 1Mbps : -94dBm maximum

802.11b, 11Mbps: -86dBm maximum 802.11g, 6Mbps: -88dBm maximum 802.11g, 54Mbps: -74dBm maximum 802.11a, 6Mbps: -86dBm maximum 802.11a, 54Mbps: -72dBm maximum 802.11n, MCS07: -69dBm maximum 802.11n, MCS15: -66dBm maximum

802.11ac, 1SS, MCS-0 : -86dBm maximum 802.11ac, 1SS, MCS-9 : -61dBm maximum 802.11ac, 2SS, MCS-0 : -83dBm maximum 802.11ac, 2SS, MCS-9 : -58dBm maximum

Antenna type High efficiency antenna with spatial diversity, mounted in the display

enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth

communications

Form Factor PCI-Express M.2 MiniCard Type 2230 : 2.3 x 22.0 x 30.0 mm

Or

Type 1630: 2.3 x 16.0 x 30.0 mm

Weight Type 2230 : 2.8g

Or

Type 1630 : 2g

Operating Voltage 3.3v +/- 9% Operating

Derature Operating 14° to 158° F (-10° to 70° C)

Non-operating -40° to 176° F (-40° to 80° C)

Humidity Operating 10% to 90% (non-condensing) Non-operating 5% to 95% (non-condensing)

Altitude Operating 0 to 10,000 ft (3,048 m)

Non-operating 0 to 50,000 ft (15,240 m)

LED Activity LED Amber - Radio OFF; LED White - Radio ON

4. Check latest software/driver release for updates on supported security features.

Maximum output power may vary by country according to local regulations.

6. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).



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HP Integrated Module with Bluetooth 4.0+EDR Wireless Technology

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 0.01% BER
 0.001% BER

 GFSK
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 -70 dBm

 8DPSK
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Power Consumption Peak (Tx) 330 mW

Peak (Rx) 230 mW

Selective Suspend 17 mW

Range Up to 33 ft (10 m)
Electrical Interface USB 2.0 compliant

Bluetooth Software Supported Microsoft Windows Bluetooth Software

Link Topology

Electrical Interface Point to Point, Multipoint Pico Nets up to 7 slaves

Bluetooth Software Supported

Security

Full support of Bluetooth Security Provisions

Power Management Microsoft Windows ACPI, and USB Bus Support

Power Management Self-configurable to optimize power conservation in all operating

Certifications modes, including Standby, Hold, Park, and Sniff

Security All necessary regulatory approvals for supported countries, inclu

Certifications FCC (47 CFR) Part 15C, Section 15.247 & 15.249

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Power Management ETS 300 328, ETS 300 826
Certifications Low Voltage Directive IEC950

UL, CSA, and CE Mark Serial Port Profile (SPP)¹

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Object Push Profile (OPP)^{1,2} File Transfer Profile (FTP) Synchronization Profile (SYNC)

Certifications
Bluetooth Profiles Supported

Hard Copy Cable Replacement (HCRP)^{1,2}

Personal Area Networking Profile (PAN)^{1,2} Human Interface Device Profile (HID)^{1,2}

FAX Profile (FAX)

Basic Imaging Profile (BIP)² Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)

Intel® Dual Band Wireless-AC 3160 802.11 ac (1x1) Wi-Fi + Bluetooth®

Wireless LAN IEEE 802.11a
Standards IEEE 802.11b
IEEE 802.11g



Technical Specifications

Interoperability Frequency Band

IEEE 802.11n IEEE 802.11ac Wi-Fi certified 802.11b/g/n

• 2.402 - 2.482 GHz

Note:

The FCC has declared as of January 1, 2015 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

802.11a/n

- 4.9 4.95 GHz (Japan)
- 5.15 5.25 GHz
- 5.25 5.35 GHz
- 5.47 5.725 GHz
- 5.825 5.850 GHz

Note:

Data Rates

Indonesia only supports 5.725 - 5.825 GHz (CH149 - CH161)

- 802.11b: 1, 2, 5.5, 11 Mbps
- 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
- 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
- 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)
 802.11ac: MCS0 ~ MCS7, (1SS) (20MHz, 40MHz,
 - and 80MHz)

Modulation

Direct Sequence Spread Spectrum

BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM

Security¹

- IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only
- AES-CCMP: 128 bit in hardware
- 802.1x authentication
- WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
- WPA2 certification
- IEEE 802.11i
- Cisco Certified Extensions, all versions through CCX4 and CCX Lite
- WAPI

Network Architecture Models

Output Power²

Roaming

Ad-hoc (Peer to Peer)

Infrastructure (Access Point Required)

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- 802.11a: +14dBm minimum
- 802.11n HT20(2.4GHz): +13dBm minimum
- 802.11n HT40(2.4GHz): +13dBm minimum
- 802.11n HT20(5GHz): +12dBm minimum
- 802.11n HT40(5GHz): +12dBm minimum
- 802.11ac 80MHz(5GHz): +11dBm minimum

Power Consumption

Transmit: 2.0 W (max) Receive: 1.6 W (max)

Idle mode (PSP): 180 mW (WLAN Associated)
Idle mode: 60 mW (WLAN unassociated)

Radio disabled: 30 mW



Technical Specifications

Power Management ACPI and PCI Express compliant power management

802.11 compliant power saving mode

Receiver Sensitivity³ 802.11b, 1Mbps : -94dBm maximum

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802.11ac, 1SS, MCS-0 : -86dBm maximum 802.11ac, 1SS, MCS-9 : -61dBm maximum 802.11ac, 2SS, MCS-0 : -83dBm maximum 802.11ac, 2SS, MCS-9 : -58dBm maximum

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Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth

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Dimensions Type 2230 : 2.3 x 22.0 x 30.0 mm

Or

Type 1630: 2.3 x 16.0 x 30.0 mm

Weight Type 2230 : 2.8g

Or

Type 1630 : 2g

Operating Voltage 3.3v +/- 9%

Temperature Operating 14° to 158° F (-10° to 70° C)

Non-operating -40° to 176° F (-40° to 80° C)

Humidity Operating 10% to 90% (non-condensing)

Non-operating 5% to 95% (non-condensing) Operating 0 to 10,000 ft (3,048 m)

Non-operating 0 to 50,000 ft (15,240 m)
LED Activity LED Amber - Radio OFF; LED White - Radio ON

7. Check latest software/driver release for updates on supported security features.

8. Maximum output power may vary by country according to local regulations.

9. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

Audio/Multimedia - DTS Sound+

Hardware Implementation Realtek ALC3228 HD

Function Key Volume

Controls

Altitude

Volume up, volume down, and mute

Full Duplex Yes
Microphone In Stereo
Headphone/Line Out Stereo

Integrated Microphone Yes, dual digital microphone array



Technical Specifications

Audio Output Quality Frequency Response 20 Hz - 20 kHz

Signal to Noise Ratio >85 dB
Total Harmonic 0.01%

Distortion

Noise Floor -110 dB Play/Record Sampling 8 kHz - 48kHz

Rate(s)

DAC 16, 20 or 24-bit **ADC** 16 or 20-bit

Integrated Stereo Speakers

Power Rating 2 Watts Impedance 4 Ohms

Security

HP Fingerprint Reader Mobile Voltage 3.0V-3.6V (optional) **Operation**

Operating Temperature 14° - 167°F (-10° - 75°C)

Current Consumption

Image

Low Latency Wait for 950 uA

Finger

Capture Rate

6000 lines/sec

36 mA peak

ESD Resistance IEC 61000-4-2 4B (±15KV)

Detection Matrix 200*1 (plus another secondary line)

508 dpi

12*3 mm sensor area

Smart Card Reader Smart card standard PC/SC 2.0 for Windows smart card standard

Dimensions (L x W x H) 0.41x 0.08 x 0.32 in (10.5 x 2 x 8.2 mm)

Smart Card support ISO 7816 Class A and AB smart cards

Smart Card Interface Smart Card Interface with T = 0 and T = 1 support

Support I2C memory card, SLE4418, SLE4428, SLE4432, SLE4442,

SLE4436,

SLE5536, SLE6636, AT88SC1608, AT45D041 card and AT45DB041

card via

external EEPROM

Operating systems No driver is required for this device. Native support is provided by the

operating system.

Power Normal Mode With card present, before being suspended: 40.9

mΑ

Without card present, before being suspended:

33.16 mA

After being suspended with smart card present:

380 µA

After being suspended without smart card present:

380 µA



Technical Specifications

Power Saving Mode

With card present, before being suspended: 40.6

mΑ

Without card present: 380 µA

After being suspended with smart card present:

Features

Support single slot

Support T0, T1 protocol

 Support I2C memory card, SLE4418, SLE4428, SLE4432, SLE4442, SLE4436,

• SLE5536, SLE6636, AT88SC1608, AT45D041 card and AT45DB041 card via external EEPROM

Support ISO7816 Class A, B and C (5V/3V/1.8V) card

 Implemented as an USB full speed device with bulk transfer endpoint, Mass

• Storage endpoint

Built-in PLL for USB and Smart Card clocks requirement

 Support EEPROM for USB descriptors customization (PID/VID/ iManufacturer/iProduct/Serial Number), Direct Web Page Link, and accessing memory card module.

• EEPROM programmable via USB interface

Support software update for memory card module

 Support Direct Web Page Link via configuration in external **EEPROM**

Support short APDU and extended APDU

Compatible with Microsoft USB-CCID driver

Support remote wake up through inserting card/removing card

Support USB selective suspend

Support Power Saving Mode (Using one pin to select between Normal/PWR Saving Mode)

• Support card power over current protection mechanism

Built in resonator.

Support USB LPM (Link Power Management) features.

Embedded clock source.

Power

HP 45W Smart AC Adapter Non-Slim & Non-Slim 2 Prong

Dimensions 95.0 x 40.0 x 26.5mm Input

90 to 265 VAC

Input Efficiency 87% min at 115 VAC// 89% min at 230VAC

Input frequency range 47 to 63 Hz

Input AC current 1.4 A at 90 VAC and maximum load

Output **Output power** 45W

DC output 19.5V

Hold-up time 5 msec at 115 VAC input

Output current limit <8A, Over voltage protection- 29V max

automatic shutdown

Connector **Operating Environmental Design**

3 pin/grounded, mates with interchangeable cords 32° to 95° F (0° to 35° C)

temperature

Non-operating (storage) -4° to 121° F (-20° to 85° C)

temperature

Altitude 0 to 16,405 ft (0 to 5,000 m)

Humidity 0% to 95% Storage Humidity 0% to 95%



Technical Specifications

EMI and Safety Certifications

CE Mark - full compliance with LVD and EMC directives; Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B. FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE; Reliability failure rate of less than 0.1% annually within the first three years of

operation.

HP 65W Smart AC Adapter

Dimensions 4.17 x 1.85 x 1.1 in (10.6 x 4.7 x 2.8 cm)

Weight 0.62 lb (280 g) Input 100 to 240 VAC

> **Input Efficiency** 87% min at 115 VAC/230VAC

Input frequency range 47 to 63 Hz

1.7 A at 90 VAC, 0.85 A at 180 VAC Input AC current

Output 65W Output power DC output 18.5V

Hold-up time

5 msec at 115 VAC input

<11A, Over voltage protection- 29V max Output current limit

automatic shutdown

HP 65W EM Smart AC Adapter

Dimensions 4.98 x 1.97 x 1.18 in (12.65 x 5.0 x 3.0 cm)

Weight 0.62 lb (300 g) max Input 90 to 265 VAC

> **Input Efficiency** 87% min at 115 VAC/230VAC

Input frequency range 47 to 63 Hz Input AC current 1.7 A at 90 VAC

Output **Output power** 65W

DC output 19.5V

Hold-up time 5 msec at 115 VAC input

Output current limit <11A, Over voltage protection- 29V max

automatic shutdown

3 pin/grounded, mates with 4.5mm barrel type Smart ID DC connector

Operating **Environmental Design** 32° to 95° F (0° to 35° C)

temperature

Non-operating (storage) -4° to 185° F (-20° to 85° C)

temperature

Altitude 0 to 16,405 ft (0 to 5,000 m)

Humidity 20% to 95% **Storage Humidity** 10% to 95%

EMI and Safety Certifications

Connector

CE Mark - full compliance with LVD and EMC directives: Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE; MTBF - over

200,000 hours at 25°C ambient condition.



Technical Specifications

3-cell HP Long Life (24WHr) Lithium-lon Polymer

Dimensions (H x W x L) 7.8 x 4.01 x 0.3 in(19.89x10.28x0.84 cm)

Weight 180g

Cells/Type 3-cell Lithium-Ion Polymer

Energy Voltage 11.1

Amp-hour capacity 2.2Ah

Watt-hour capacity 24Wh

Temperature Operating (Charging) 32° to 113° F (0° to 45° C)

Operating (Discharging) 14° to 140° F(-10° to 50° C) Non-operating -4° to 140° F (-20° to 50° C)

Battery System in OFF or 3 hours

Re-Charge Time Standby Mode

Fuel Gauge LED No

Warranty 1 year or 3 years*

*Battery warranty depends on the platform warranty.

Optional Travel Battery No

Available

3-cell HP Long Life (50WHr) Lithium-lon Polymer

Dimensions (H x W x L) 7.8 x 4.01 x 0.3 in(19.89x10.28x0.84 cm)

Weight 280 g

Cells/Type 3-cell Lithium-Ion Polymer

Energy Voltage 11.1

Amp-hour capacity 4.504Ah Watt-hour capacity 50Wh

Temperature Operating (Charging) 32° to 113° F (0° to 45° C)

Operating (Discharging) 14° to 140° F(-10° to 60° C) Non-operating -4° to 140° F (-20° to 60° C)

Battery System in OFF or 3 hours

Re-Charge Time Standby Mode

Fuel Gauge LED No

Warranty 1 year or 3 years*

*Battery warranty depends on the platform warranty.

Optional Travel Battery No

Available



Technical Specifications

6-cell HP Long Life (60WHr) Lithium-lon Polymer

Dimensions (H x W x L) 12.59 x 8.6 x 0.59 in (32 x 21.85 x 1.51cm)

Weight 603 g

Cells/Type 3-cell Lithium-Ion Polymer

Energy Voltage 11.1

Amp-hour capacity 5.4Ah Watt-hour capacity 60 Wh

Temperature Operating (Charging) 32° to 113° F (0° to 45° C)

Operating (Discharging) 14° to 140° F(-10° to 60° C) Non-operating -4° to 140° F (-20° to 60° C)

3 hours

Battery System in OFF or

Re-Charge Time Standby Mode

Fuel Gauge LED Yes

Warranty 1 year or 3 years*

*Battery warranty depends on the platform warranty.

Optional Travel BatteryYes

Available

ENVIRONMENTAL

Eco-Label
Certifications & declarations

This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

- IT ECO declaration
- US ENERGY STAR®
- EPEAT Gold registered in the United States. See http://www.epeat.net for registration status in your country.

System Configuration

The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a "Typically Configured Notebook".

Energy
Consumption
(in
accordance
with US
ENERGY
STAR® test
method)
Normal

STAR® test method) Normal	115VAC, 60Hz 8.59 W	230VAC, 50Hz 8.92 W	100VAC, 60Hz 8.65 W
Operation			
(Short idle)			
Normal	3.39 W	3.87 W	4.47 W
Operation			
(Long idle)			
Sleep	0.74 W	0.79 W	0.74 W
Off	0.36 W	0.4 W	0.35 W

Note:

Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive,



Technical Specifications

a high efficiency power supply, and a Microsoft Windows® operating system.

Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz
Normal Operation	29 BTU/hr	31 BTU/hr	30 BTU/hr
(Short idle) Normal Operation (Long idle)	12 BTU/hr	13 BTU/hr	15 BTU/hr
Sleep Off	3 BTU/hr 1 BTU/hr	3 BTU/hr 1 BTU/hr	3 BTU/hr 1 BTU/hr

*NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Declared Noise Emissions (in accordance with ISO 7779 and	Sound Power (L _{WAd} , bels)	Sound Pressure (L _{pAm} , decibels)
ISO 9296) Typically Configured -	2.9	21
Idle Fixed Disk - Random writes Batteries	3.0 This battery(s) in this product comply with EU Directive 2006/66/EC	22

Batteries used in the product do not contain:

Mercury greater the1ppm by weight

Cadmium greater than 20ppm by weight

Battery size: CR2032 (coin cell)

Battery type: Lithium

Battery size: 6-cell high capacity Lithium-Ion battery (optional 8 cell available)

Battery type:

Additional Information

- This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC.
- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive - 2002/96/EC.
- This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).
- This product is in compliance with the IEEE 1680 (EPEAT) standard at the Gold level, see www.epeat.net
- Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043.



Technical Specifications

- This product contains 0 % post-consumer recycled plastic (by wt.)
- This product is 97.3 % recycle-able when properly disposed of at end of life.

Packaging Materials

External: PAPER/Corrugated 405 g

Internal: PLASTIC/EPE (Expanded Polyethylene) 45 g

PLASTIC/Polyethylene low density 26 g

The PAPER/Corrugated packaging material is made from 70 % recycled content. The PLASTIC/EPE (Expanded Polyethylene) materials contains at least 50% recycled content.

Material Usage

The PLASTIC/Polyethylene low density) materials contains at least 50% recycled content. This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf):

- Asbestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants may not be used as flame retardants in plastics
- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Formaldehyde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

Packaging Usage

HP follows these guidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

End-of-life Management and Recycling

Hewlett-Packard offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.



Technical Specifications

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

Hewlett-Packard Corporate Environmental Information For more information about HP's commitment to the environment:

Global Citizenship Report

http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html

Eco-label certifications

http://www8.hp.com/us/en/hp-information/environment/ecolabels.html

ISO 14001 certificates:

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K_Certificate.pdf

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

Country of Origin

China



Summary of Changes

Type Cases	Description HP Slim Ultrabook Messenger (up to 15.6" x .88"/22/5mm)	Part # F3W14AA
Dooking	HP Slim Ultrabook Top Load (up to 15.6" x .88"/22/5mm)	F3W15AA F3S42AA
Docking	HP 3001pr USB 3 Port Replicator HP 3005pr USB 3.0 Port Replicator	H1L08AA#
	HP UltraSlim Docking Station	D9Y32AA#
	HP Universal Port Replicator	E6D70AA#
	HP Display and Notebook Stand	AW662AA
Input/Output - Mice	HP Comfort Grip Wireless Mouse	H2L63AA
mpad Oatpat - Milce	HP X4000b Bluetooth Mouse	H3T50AA#
	HP 3-Button USB Laser Mouse	H4B81AA
	HP Ultra Mobile Wireless Mouse	H6F25AA#
	HP Slim Bluetooth Mouse	F3J92AA#)
Input/Output - Keyboards	HP Stylish USB Keyboard and Mouse	H4B80AA#
mpad carput Troyscarac	HP Stylish Wireless Keyboard and Mouse	H4B79AA#
	HP USB Essential Keyboard and Mouse	H6L29AA
	HP 2.4 GHz Keyboard and Mouse	G1K29AA#
Input/Output - Adapters	HP Wireless Display Adapter	J1V25AA#
	DisplayPort to VGA	F7W97AA
	USB Graphic adapter Dual output	C5U89AA
	DisplayPort to DVI Adapter	F7W96AA
	DisplayPort to HDMI Cable	F3W43AA
Power	HP 65W Slim AC Adapter	H6Y82AA#
	HP 90W Slim AC Adapter	H6Y83AA#
	HP 90W Slim Combo AC Adapter w/USB	H6Y84AA#
	HP 45W Smart AC Adapter	H6Y88AA#
	HP 65W Smart AC Adapter	H6Y89AA#
	HP 90W Smart AC Adapter	H6Y90AA#
	HP 90W Smart AC/Auto/Air Combo Adapter	AJ652AA#
	HP 90W Smart Auto/Truck Adapter	ED493AA
Batteries	HP CO06XL Notebook Battery (Slice)	E7U23AA
_	HP CM03XL Notebook Battery	E7U24AA
Security	HP Docking Station Cable Lock	AU656AA#)
	HP UltraSlim Keyed Cable Lock	H4D73AA
Storage - External Storage	HP USB External DVDRW Drive	F2B56AA
Misc.	HP 14" Notebook PC Privacy Filter	J6E65AA
Displays	HP EliteDisplay S231d 23-in IPS LED BLU Notebook Docking	E0)4/04 A A
	Monitor	F0W81AA
	HP EliteDisplay S240ml 23.8-in IPS LED Backlit MHL Monitor	F4M47AA F0W81AA
	HP EliteDisplay E241i 24-in IPS LED Backlit Monitor	FUVVOTAA



Summary of Changes

Date of change:	Version History:		Description of change:
January 20, 2015	Version 1 to 2	Added	The words "up to" to all battery life specs
January 26, 2015	V2 to V3	Added	Environmental information and stand by time
March 18, 2015	V3 to V4	Changed	Memory unit speed spec on page 8
April 10, 2015	V4 to V5	Removed	Surface Treatment Anti Glare page 16 and 17
June 29, 2015	V5 to V6	Added	Windows 10 in overview on page 4, OS list on page 5, footnotes
			on page 5 and 8
		Updated	TPM Embedded Security Chip to 1.2
		Removed	2013 from name of HP UltraSlim Docking Station
		Updated	Removed HP CA06XL Notebook Battery E7U21AA
January 11, 2016	V6 to V7		Added HP CM03XL Notebook Battery E7U24AA
•			Amount of post-consumer recycled plastic value is changed to 0%
January 20, 2016	040 \\(\sqrt{7.15.\sqrt{9}} \) Ac	Added	BIOS adheres to NIST SP800-147 to footnote 3 in Software BIOS
	V7 to V8		section
January 20, 2016		Removed	A period from footnote 3 in Software BIOS section

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